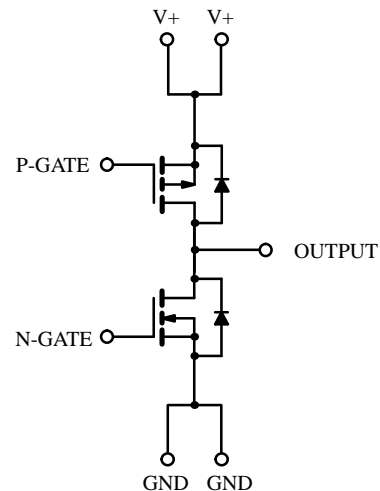
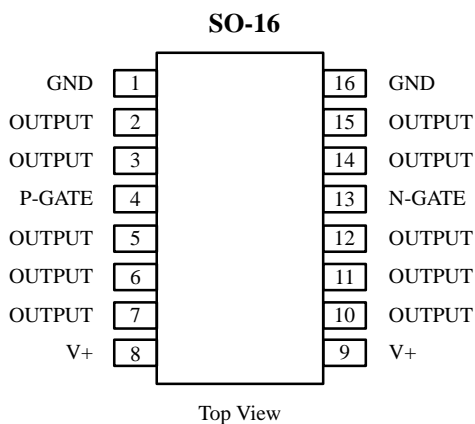


Complementary MOSFET Half-Bridge

Product Summary

	V _{DS} (V)	r _{DS(on)} (Ω)	I _D (A)
N- or P-Channel	50	0.3 @ V _{GS} = 10 V	± 2.0
		1.0 @ V _{GS} = 5 V	± 1.2

Alternate Solution: one Si9948DY and one Si9945DY



Absolute Maximum Ratings (T_A = 25°C Unless Otherwise Noted)

Parameter	Symbol	N- or P-Channel	Unit
Drain-Source Voltage	V _{DS}	50	V
Gate-Source Voltage	V _{GS}	± 20	
Continuous Drain Current (T _J = 150°C) ^a	T _A = 25°C	± 2.0	A
	T _A = 70°C	± 1.7	
Pulsed Drain Current	I _{DM}	± 8	
Continuous Source Current (Diode Conduction) ^a	I _S	2.8	
Maximum Power Dissipation ^a	T _A = 25°C	2.3	W
	T _A = 70°C	1.5	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55 to 150	°C

Thermal Resistance Ratings

Parameter	Symbol	N- or P-Channel	Unit
Maximum Junction-to-Ambient ^a	R _{thJA}	55	°C/W

Notes

a. Surface Mounted on FR4 Board, t ≤ 10 sec.

Updates to this data sheet may be obtained via facsimile by calling Siliconix FaxBack, 1-408-970-5600. Please request FaxBack document #70136.

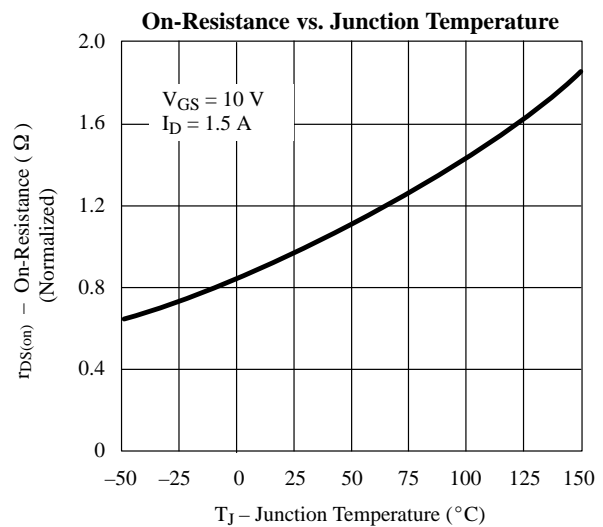
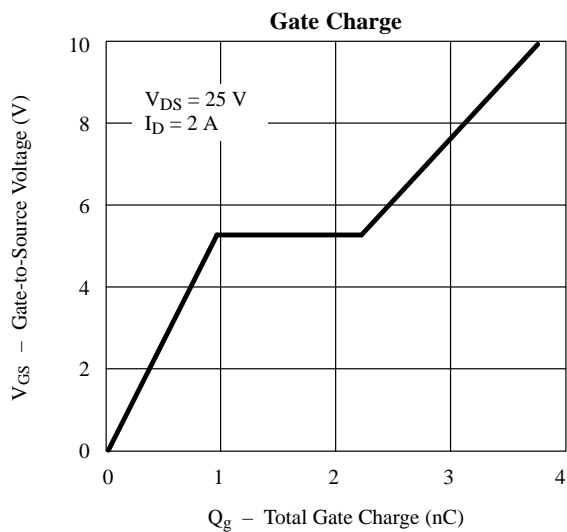
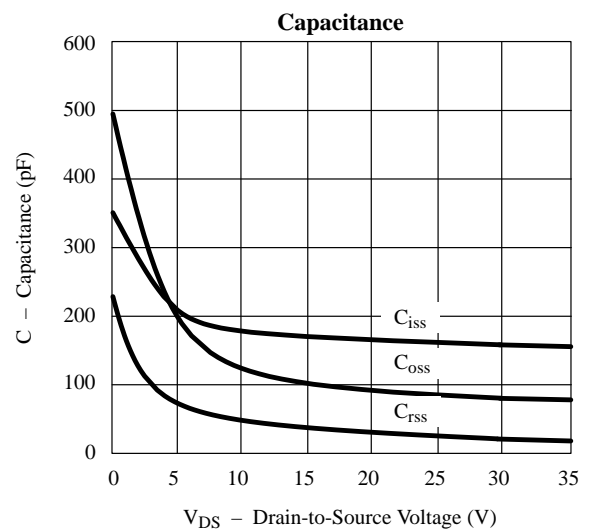
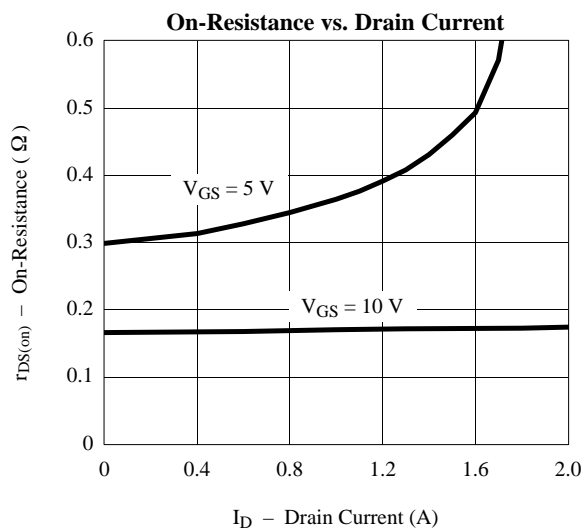
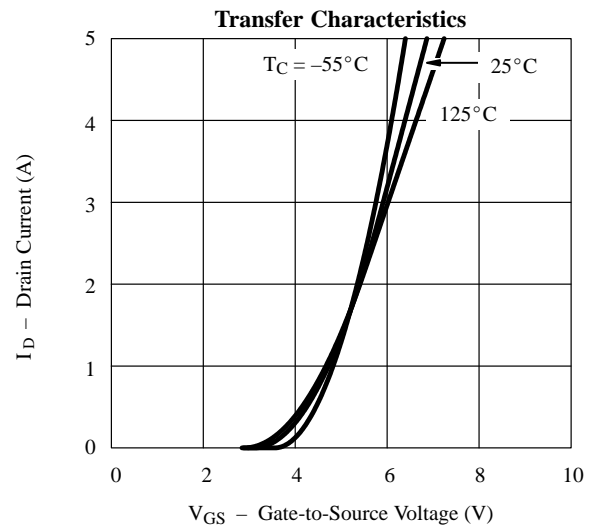
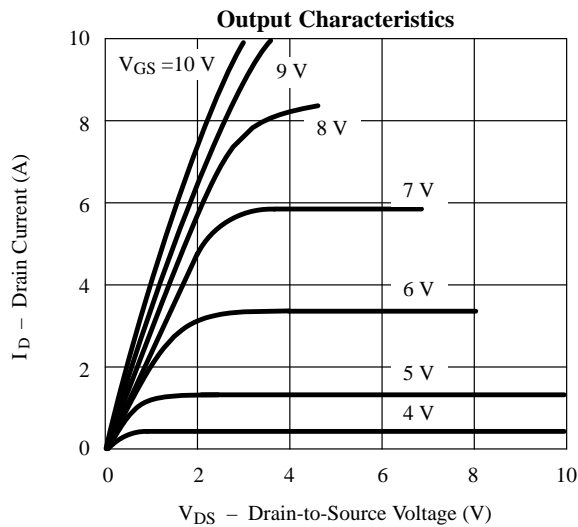
Specifications ($T_J = 25^\circ\text{C}$ Unless Otherwise Noted)

Parameter	Symbol	Test Condition	Min	Typ ^a	Max	Unit	
Static							
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	N-Ch	2.0		V	
		$V_{DS} = V_{GS}, I_D = -250 \mu\text{A}$	P-Ch	-1.5			
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}$	N-Ch		2	μA	
		$V_{DS} = -40 \text{ V}, V_{GS} = 0 \text{ V}$	P-Ch		-2		
		$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 55^\circ\text{C}$	N-Ch		25		
		$V_{DS} = -40 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 55^\circ\text{C}$	P-Ch		-25		
On-State Drain Current ^b	$I_{D(on)}$	$V_{DS} \geq 5 \text{ V}, V_{GS} = 10 \text{ V}$	N-Ch	8		A	
		$V_{DS} \leq -5 \text{ V}, V_{GS} = -10 \text{ V}$	P-Ch	-8			
Drain-Source On-State Resistance ^b	$r_{DS(on)}$	$V_{GS} = 10 \text{ V}, I_D = 1 \text{ A}$			0.3	Ω	
		$V_{GS} = 5 \text{ V}, I_D = 0.5 \text{ A}$			1.0		
Forward Transconductance ^b	g_{fs}	$V_{DS} = 15 \text{ V}, I_D = 1 \text{ A}$	N-Ch		1.1	S	
		$V_{DS} = -15 \text{ V}, I_D = -1 \text{ A}$	P-Ch		1.4		
Diode Forward Voltage ^b	V_{SD}	$I_S = 2 \text{ A}, V_{GS} = 0 \text{ V}$	N-Ch		0.9	V	
		$I_S = -2 \text{ A}, V_{GS} = 0 \text{ V}$	P-Ch		-1.3		
Dynamic^a							
Total Gate Charge	Q_g	N-Channel $V_{DS} = 25 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 2 \text{ A}$ P-Channel $V_{DS} = -25 \text{ V}, V_{GS} = -10 \text{ V}, I_D = -2 \text{ A}$	N-Ch		3.7	6.0	nC
Gate-Source Charge	Q_{gs}		N-Ch		1.0		
Gate-Drain Charge	Q_{gd}		N-Ch		1.2		
Turn-On Delay Time	$t_{d(on)}$	N-Channel $V_{DD} = 25 \text{ V}, R_L = 25 \Omega$ $I_D \cong 1 \text{ A}, V_{GEN} = 10 \text{ V}, R_G = 6 \Omega$ P-Channel $V_{DD} = -25 \text{ V}, R_L = 25 \Omega$ $I_D \cong -1 \text{ A}, V_{GEN} = -10 \text{ V}, R_G = 6 \Omega$	N-Ch		7	20	ns
Rise Time	t_r		N-Ch		13	30	
			P-Ch		25	50	
Turn-Off Delay Time	$t_{d(off)}$		N-Ch		18	40	
			P-Ch		65	100	
Fall Time	t_f		N-Ch		13	25	
		P-Ch		60	100		
Source-Drain Reverse Recovery Time	t_{rr}	$I_F = 2 \text{ A}, di/dt = 100 \text{ A}/\mu\text{s}$	N-Ch		70	100	
			P-Ch		70	100	

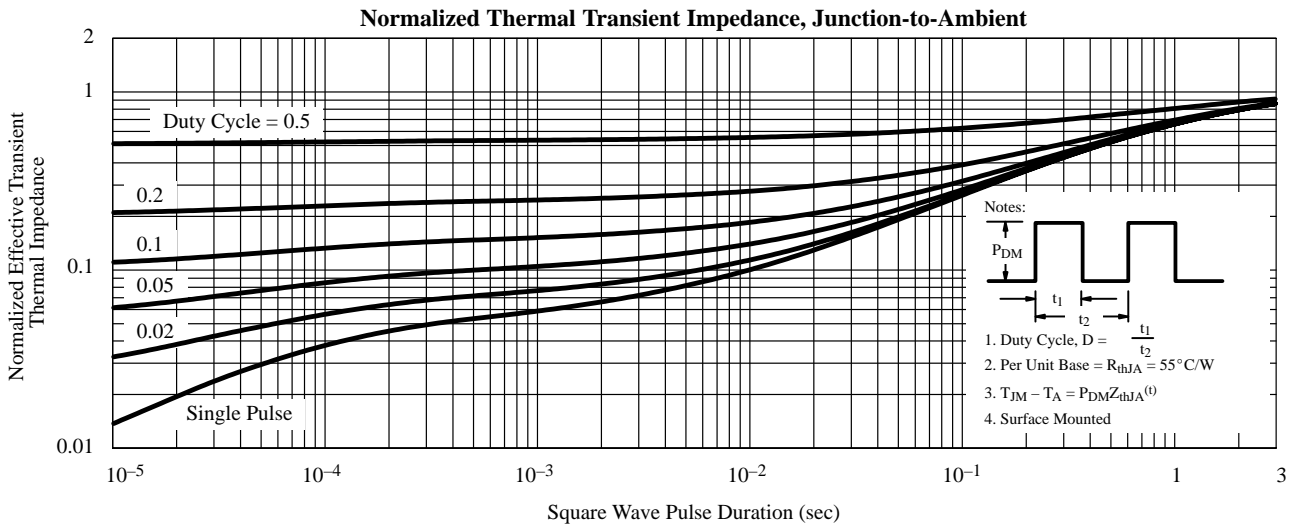
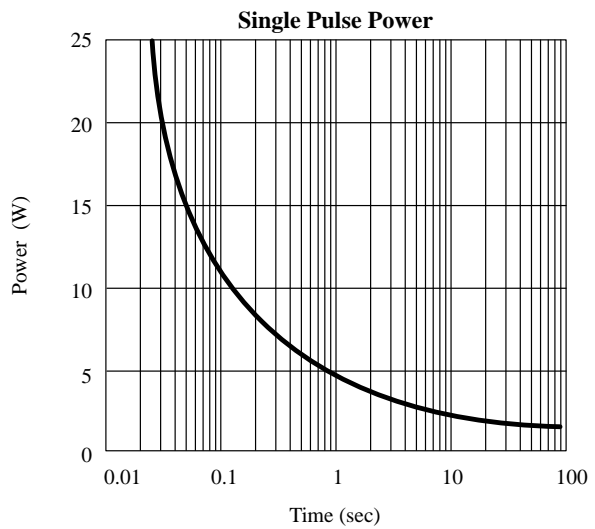
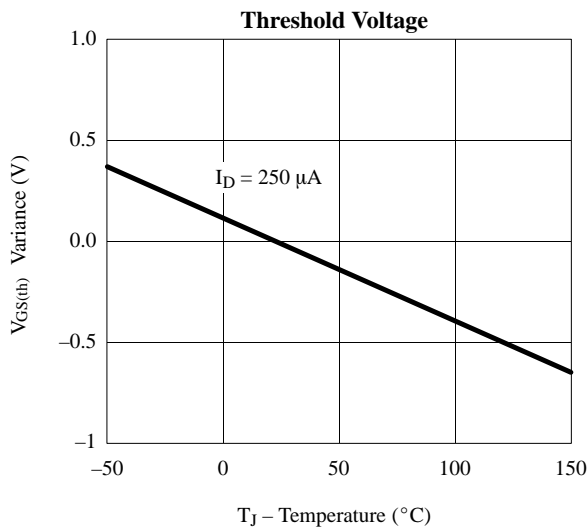
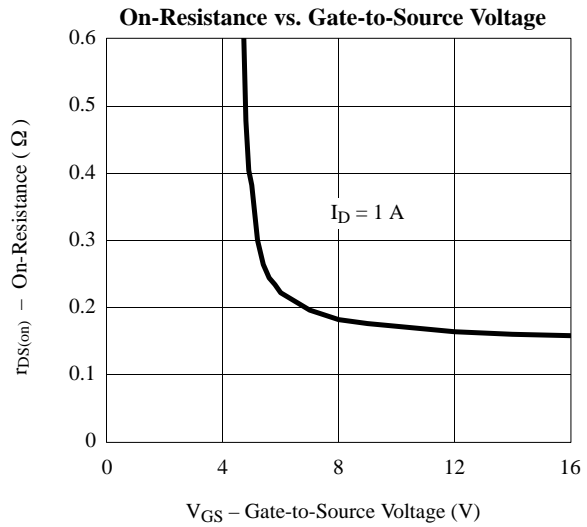
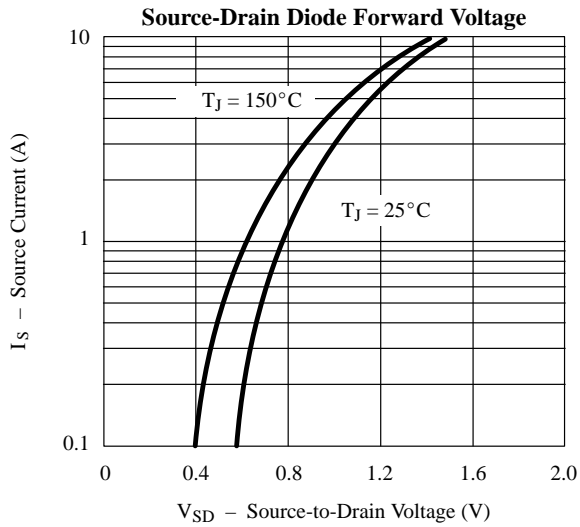
Notes

- a. Guaranteed by design, not subject to production testing.
 b. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.

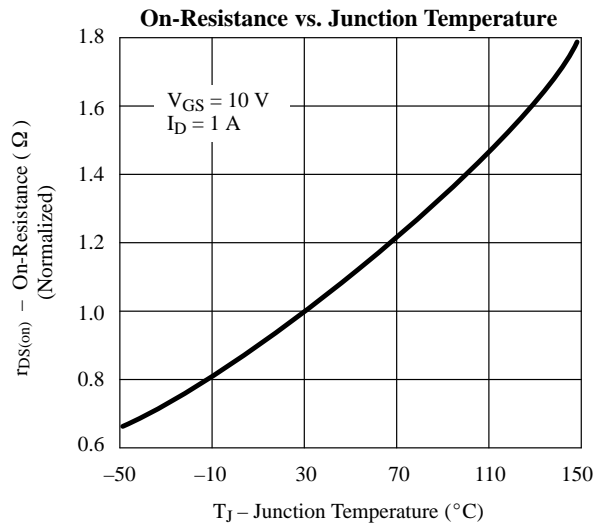
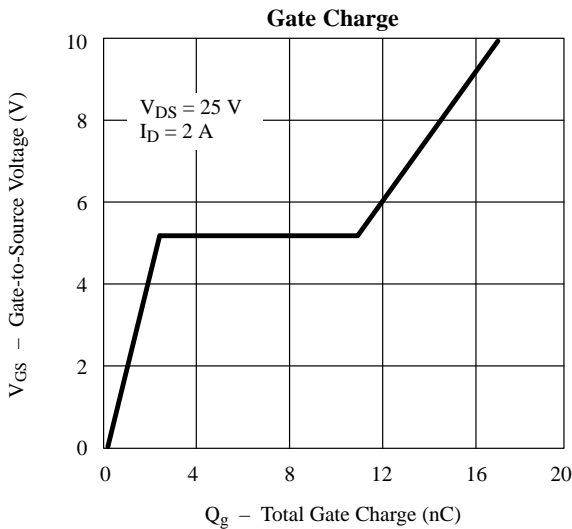
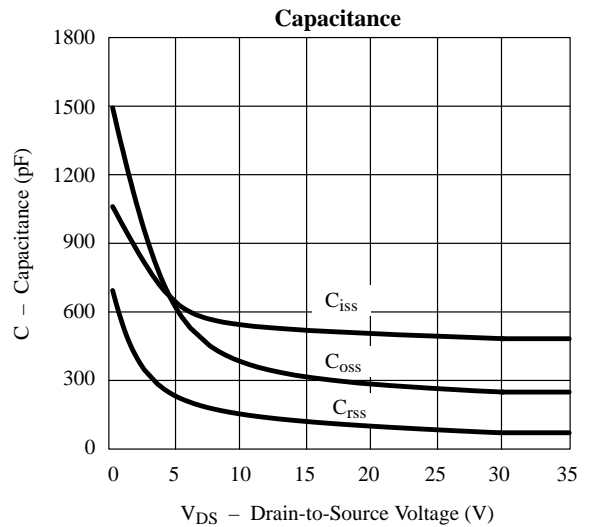
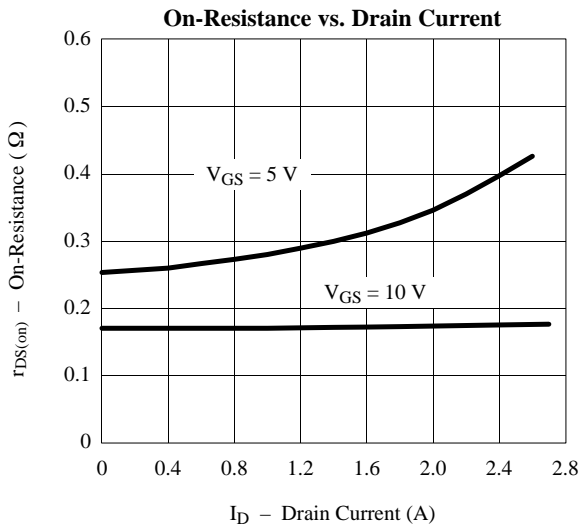
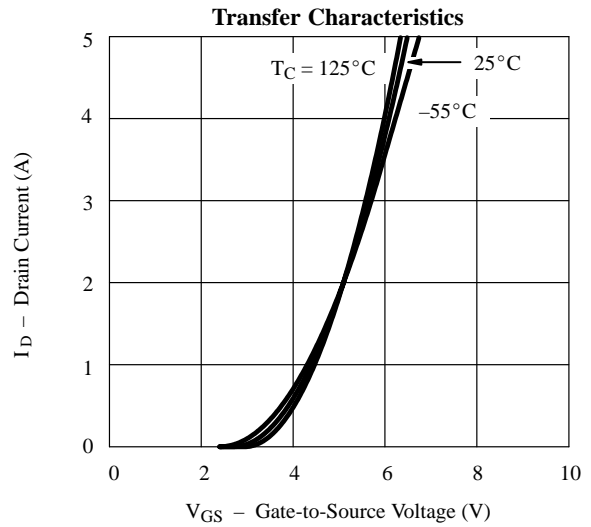
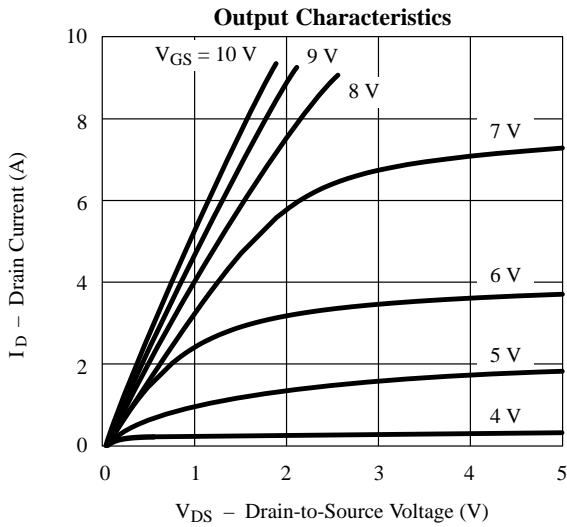
Typical Characteristics (25°C Unless Otherwise Noted) N-Channel



Typical Characteristics (25°C Unless Otherwise Noted) N-Channel



Typical Characteristics (25°C Unless Otherwise Noted) P-Channel



Typical Characteristics (25°C Unless Otherwise Noted) P-Channel

